

HSM88ASR

Silicon Schottky Barrier Diode for Balanced Mixer

REJ03G0136-0500Z

(Previous: ADE-208-047D)

Rev.5.00 Nov.06.2003

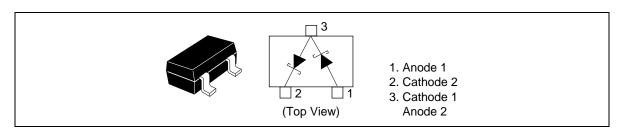
Features

- Proof against high voltage.
- MPAK package is suitable for high density surface mounting and high speed assembly.

Ordering Information

Type No.	Laser Mark	Package Code
HSM88ASR	C3	MPAK

Pin Arrangement



Absolute Maximum Ratings

 $(Ta = 25^{\circ}C)$

Item	Symbol	Value	Unit
Reverse voltage	V_R	10	V
Average rectified current	I ₀ *1	15	mA
Junction temperature	Tj	125	°C
Storage temperature	Tstg	-55 to +125	°C

Note: 1. Per one device

Electrical Characteristics *1

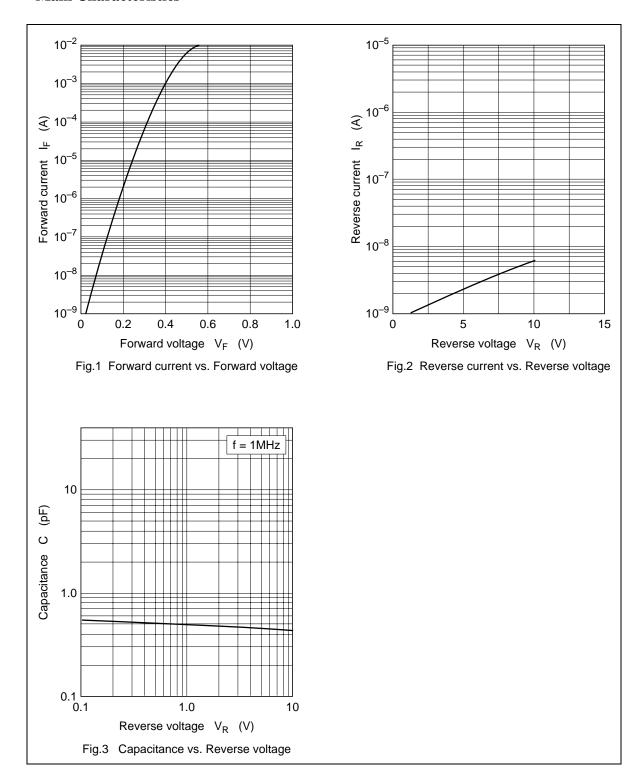
 $(Ta = 25^{\circ}C)$

Item	Symbol	Min	Тур	Max	Unit	Test Condition
Forward voltage	V_{F1}	0.35	_	0.42	V	I _F = 1 mA
	V _{F2}	0.50	_	0.58	='	I _F = 10 mA
Reverse current	I _{R1}	_	_	0.2	μΑ	V _R = 2 V
	I _{R2}	_	_	10	='	V _R = 10 V
Capacitance	С	_	_	0.85	pF	V _R = 0 V, f = 1 MHz
Capacitance deviation	ΔC	_	_	0.10	рF	$V_R = 0 V, f = 1 MHz$
Forward voltage deviation	ΔV_{F}	_	_	10	mV	I _F = 10 mA
ESD-Capability *2	_	30	_	_	V	$C = 200 \text{ pF}, R = 0 \Omega$, Both forward and reverse direction 1 pulse.

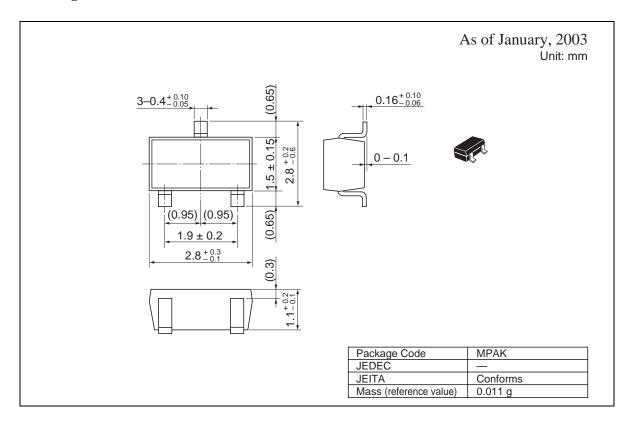
Notes: 1. Per one device

2. Failure criterion ; $I_R \geq 0.4~\mu\text{A}$ at V_R = 2 V

Main Characteristics



Package Dimensions



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